

Accepted Manuscript

Diffusion bonding of aluminum-magnesium using cold rolled copper interlayer

Javad Varmazyar, Mohammad Khodaei

PII: S0925-8388(18)33578-3

DOI: [10.1016/j.jallcom.2018.09.320](https://doi.org/10.1016/j.jallcom.2018.09.320)

Reference: JALCOM 47739

To appear in: *Journal of Alloys and Compounds*

Received Date: 11 July 2018

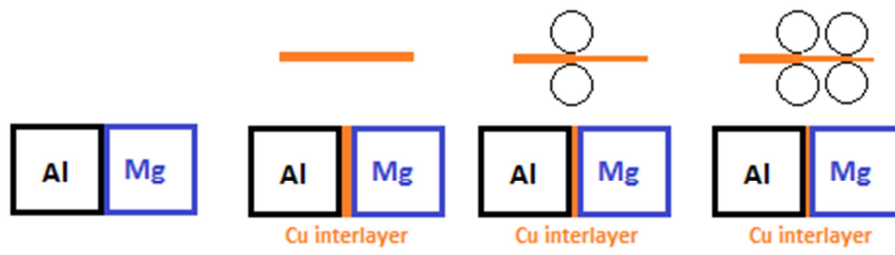
Revised Date: 24 September 2018

Accepted Date: 25 September 2018

Please cite this article as: J. Varmazyar, M. Khodaei, Diffusion bonding of aluminum-magnesium using cold rolled copper interlayer, *Journal of Alloys and Compounds* (2018), doi: <https://doi.org/10.1016/j.jallcom.2018.09.320>.

This is a PDF file of an unedited manuscript that has been accepted for publication. As a service to our customers we are providing this early version of the manuscript. The manuscript will undergo copyediting, typesetting, and review of the resulting proof before it is published in its final form. Please note that during the production process errors may be discovered which could affect the content, and all legal disclaimers that apply to the journal pertain.





Mechanical properties improvement of diffusion bonded Al-Mg

ACCEPTED MANUSCRIPT

Download English Version:

<https://daneshyari.com/en/article/11020047>

Download Persian Version:

<https://daneshyari.com/article/11020047>

[Daneshyari.com](https://daneshyari.com)